

AMENDMENT UNDER 37 C.F.R. § 1.116
EXPEDITED PROCEDURE
GROUP 2823
PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q79041

Youichi KUKIMOTO, et al.

Appln. No.: 10/765,931

Group Art Unit: 2823

Confirmation No.: 1863

Examiner: Khiem D. NGUYEN

Filed: January 29, 2004

For: SOLDER DISPOSITION METHOD AND SOLDER BUMP FORMING METHOD

AMENDMENT UNDER 37 C.F.R. § 1.116

MAIL STOP AF

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated February 7, 2007, please amend the above-identified application as follows on the accompanying pages. A Petition for a one-month Extension of Time is being concurrently filed, extending the period of response from May 7, 2007 to June 7, 2007.

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DO NOT ENTER
K.N.
06/19/07